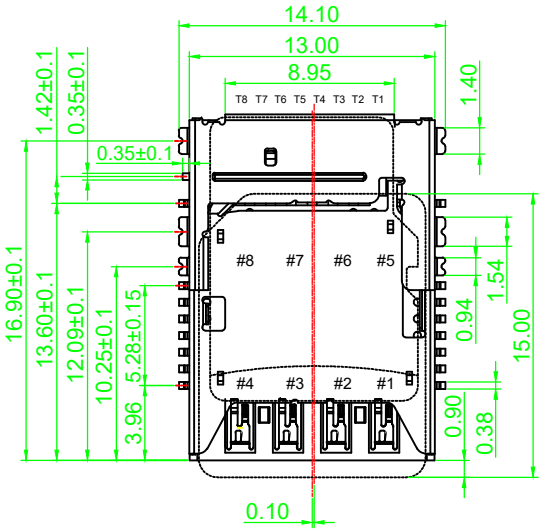
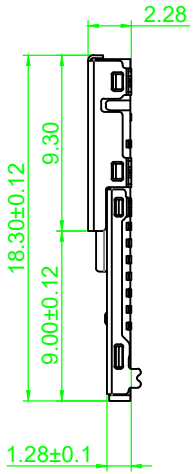
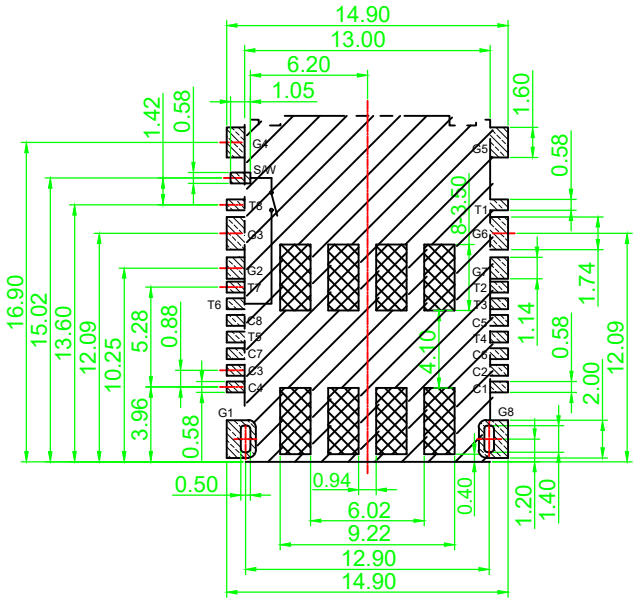
Rev.	Description.	Date	App.
01			



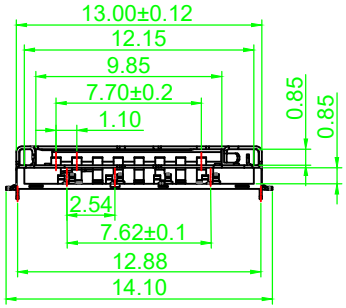


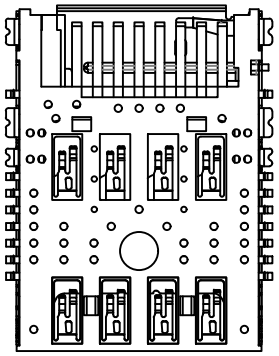


NOTES:
1.MATERIAL:
HOUSING: LCP, UL94V-0, WHITE
CONTACT: PHOSPHOR BRONZE
SHELL: SUS304

2.FINISH:
CONTACT:
CONTACT AREA: G/F GOLD PLATED
SOLDER AREA: G/F GOLD PLATED
UNDER PLATING: NICKEL PLATED
SHELL:
SOLDER AREA: NICKEL FLASH PLATED
UNDER PLATING: NICKEL PLATED.

3.SPECIFICATION:
CURRENT RATING: 0.5A / (1PIN)
DIELECTRIC WITHSTANDING: 500V AC FOR 1 MINUTE
CONTACT RESISTANCE: 100mΩ MAX.
INSULATION RESISTANCE: 500MΩ MIN.
OPERATING TEMPERATURE: -20°C ~ +85°C
DURABILITY: 1500 CYCLES MIN.
INSERTION FORCE: 20N MAX.
WITHDRAWAL FORCE: 1N



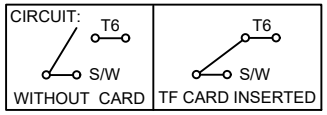


NO PATTERN AREA
NO CIRCUIT AREA
SOLDER AREA

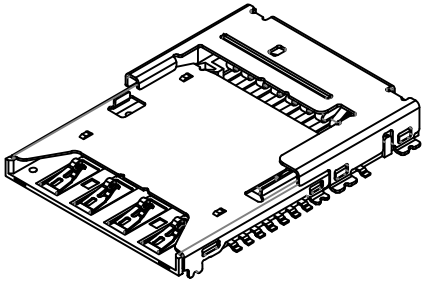
P.C.B LAYOUT (TOLERANCE:±0.05)

TF CARD PIN ASSIGNMENT	
PIN NO.	NAME
T1	DAT2
T2	CD/DAT3 [2]
T3	CMD
T4	VDD
T5	CLK
T6	VSS
T7	DAT0
T8	DAT1

G1~G8	GND



SIM PIN ASSIGNMENT	
PIN NO.	NAME
C1	VCC
C2	RST
C3	CLK
C4	RESERVED
C5	GND
C6	VPP
C7	I/O
C8	RESERVED



研騰國際企業股份有限公司
YANNIS ELECTRONICS CO.,LTD

PROJECTION:	UNIT: mm	GENERAL TOLERANCES: .X ±0.3 X°. ±3° .XX ±0.2 .X° ±1° .XXX ±0.1	APPROVED	David	SHEET: 1 OF 1	REV.: A	NAME	Micro SD + Micro SIM Combo Type H:2.28mm
	SCALE: Free		CHECKED	Sunny				
			DRAWN	Juno	DATE: 2021/02/02		PART NO.	MSD-0115000 DWG NO. MSD-0115000_01